Variant: 001
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ISE4018 REV E4 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		ISE4018	Any	Printed Circuit Board	
2	BT1	1		BS-7	Memory Protection Devices	Battery Holder, CR2032, Retainer clip, TH	CR2032 holder
3	C1	1	100uF	C3216X5R1A107M160AC	TDK	CAP, CERM, 100 µF, 10 V, +/- 20%, X5R, 1206_190	1206_190
4	C2, C9, C11, C13, C21	5	0.1uF	GRM155R70J104KA01D	MuRata	CAP, CERM, 0.1 µF, 6.3 V, +/- 10%, X7R, 0402	0402
5	C4, C7	2	2200pF	C1005X7R1H222K	TDK	CAP, CERM, 2200 pF, 50 V, +/- 10%, X7R, 0402	0402
6	C5	1	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0402	0402
7	C10	1	1uF	GRM188R70J105KA01D	MuRata	CAP, CERM, 1 µF, 6.3 V, +/- 10%, X7R, 0603	0603
8	C12, C16	2	10uF	GRM21BR70J106KE76L	MuRata	CAP, CERM, 10 µF, 6.3 V, +/- 10%, X7R, 0805	0805
9	C17, C18	2	12pF	06035A120JAT2A	AVX	CAP, CERM, 12 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
10	C19, C22, C24	3	1pF	GRM1555C1H1R0CA01D	MuRata	CAP, CERM, 1 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
11	C20	1	6.8pF	GRM1555C1H6R8CA01D	MuRata	CAP, CERM, 6.8 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
12	C25	1	12pF	GRM1555C1H120JA01D	MuRata	CAP, CERM, 12 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
13	D1	1	5V	1SS315TPH3F	Toshiba	Diode, Schottky, 5 V, 0.03 A, SOD-323	SOD-323
14	GND, SCL, SDA, VDDR, VDDS	5	SMT	5015	Keystone	Test Point, Miniature, SMT	Testpoint_Keystone_Miniature
15	H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
16	H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
17	J1, J2	2		61300211121	Wurth Elektronik eiSos	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
18	J6	1		GRPB052VWVN-RC	Sullins Connector Solutions	Header, 50mil, 5x2, Gold, TH	Header, 5x2, 50mil
19	L1, L6	2	2 nH	LQG15HS2N0S02D	MuRata	Inductor, Multilayer, Air Core, 2 nH, 0.3A, 0.1 ohm, SMD	0402 polarized
20	L2	1	1500 ohm	BLM18HE152SN1D	MuRata	Ferrite Bead, 1500 ohm @ 100MHz, 0.5A, 0603_950	0603_950
21	L3	1	10uH	CKS2125100M-T	Taiyo Yuden	Inductor, Multilayer, Ferrite, 10uH, 0.11A, 0.52 ohm, SMD	0805
22	L4, L5	2	2.4nH	LQG15HN2N4S02D	MuRata	Inductor, Multilayer, Air Core, 2.4nH, 0.3A, 0.16 ohm, SMD	0402 polarized
23	nRST, USR	2		B3U-1000P	Omron Electronic Components	SWITCH TACTILE SPST-NO 0.05A 12V	3x1.6x2.5mm
24	R1	1	12.1	CRCW080512R1FKEA	Vishay-Dale	RES, 12.1, 1%, 0.125 W, 0805	0805
25	R2	1	40.2k	CRCW040240K2FKED	Vishay-Dale	RES, 40.2 k, 1%, 0.063 W, 0402	0402
26	R3, R6, R8, R10, R26	5	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
27	R4	1	48.7k	CRCW040248K7FKED	Vishay-Dale	RES, 48.7 k, 1%, 0.063 W, 0402	0402
28	R5, R7, R15, R17	4	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
29	R11, R12	2	47.5k	CRCW040247K5FKED	Vishay-Dale	RES, 47.5 k, 1%, 0.063 W, 0402	0402
30	SH-J1	1	1x2	2SN-BK-G	Samtec	Shunt, 2mm, Gold plated, Black	2mm Shunt, Closed Top
31	U1	1		TPL5110DDC	Texas Instruments	Ultra-Low Power System Timer with MOS driver and manual MSFET power ON, DDC0006A	DDC0006A
32	U2	1		TS5A3160DBV	Texas Instruments	1-Ohm SPDT ANALOG SWITCH 5-V/3.3-V SINGLE-CHANNEL 2:1 MULTIPLEXER/DEMULTIPLEXER, DBV0006A	DBV0006A
33	U4	1		HDC1010YPAR	Texas Instruments	Low Power, High Accuracy Digital Humidity Sensor with Temperature Sensor, YPA0008AGAE	YPA0008AGAE
34	U5, U7, U9, U10	4		TPD1E10B06DPYR	Texas Instruments	ESD in 0402 Package with 10 pF Capacitance and 6 V Breakdown, 1 Channel, -40 to +125 degC, 2-pin X2SON (DPY), Green (RoHS & no Sb/Br)	DPY0002A
35	U8	1		CC2650F128RSMR	Texas Instruments	Ultra low-power ARM Cortex M3 2.4 GHz Radio MCU, RSM0032B	RSM0032B
36	Y1	1		FC-12M 32.7680KA-A3	Epson	Crystal, 32.768kHz, 12.5pF, SMD	Crystal 2.05x.6x1.2mm
37	Y2	1		TSX-3225 24.0000MF20G-AC3	Epson	Crystal, 24 MHz, 9 pF, SMD	SMD, 4-Leads, Body 2.65x3.35mm, Height 0.6mm
38	C3, C26, C27	0		Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0402
39	C6, C28, C29, C30, C31	0		Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	1206
40	C8, C14, C15	0		Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603
41	FID1, FID2, FID3, FID4, FID5, FID6	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
42	J7	0		GRPB041VWVN-RC	Sullins Connector Solutions	Header, 50mil, 4x1, Gold, TH	TH, Header, 1.27 mm, 4x1, Straight
43	J8	0		SMA-10V21-TGG	Hus-Tsan Group Co., Ltd.	Connector, SMA, Vertical, Gold, SMD	SMD, 4-Leads, Body 7.1x7.1mm
44	R9, R14	0		Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	0402

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